Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

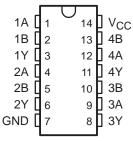
These devices contain four independent 2-input positive-AND gates. They <u>perform</u> the Boolean functions $Y = A \cdot B$ or $Y = \overline{A} + \overline{B}$ in positive logic.

The SN54ALS08 and SN54AS08 are characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ALS08 and SN74AS08 are characterized for operation from 0°C to 70°C.

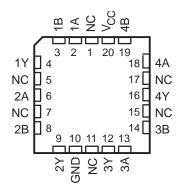
FUNCTION TABLE (each gate)

INP	UTS	OUTPUT
Α	В	Y
Н	Н	Н
L	X	L
X	L	L

SN54ALS08, SN54AS08 . . . J PACKAGE SN74ALS08, SN74AS08 . . . D OR N PACKAGE (TOP VIEW)



SN54ALS08, SN54AS08 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

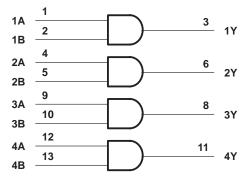
logic symbol†

1Δ	1	&	3	
1A 1B 2A 2B 3A	2	α		1Y
24	4			
28	5		6	2Y
2B	9			
3A	10		8	3Y
3B	12			
4A 4B	13		11	4Y
4B				

[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the D, J, and N packages.

logic diagram (positive logic)



SN54ALS08, SN54AS08, SN74ALS08, SN74AS08 QUADRUPLE 2-INPUT POSITIVE-AND GATES

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}	 7 \
Input voltage, V _I	 7 V
Operating free-air temperature range, T _A : SN54ALS08	 −55°C to 125°C
SN74ALS08	 0°C to 70°C
Storage temperature range	 -65°C to 150°C

recommended operating conditions

		SN54ALS08			SN	8	UNIT			
		MIN	NOM	MAX	MIN	NOM	MAX	UNII		
Vсс	Supply voltage	4.5	5	5.5	4.5	5	5.5	V		
V_{IH}	High-level input voltage	2			2			V		
\/	Law lavel in out value			0.8‡			0.8	V		
VIL	Low-level input voltage			0.7§				v l		
ІОН	High-level output current			-0.4			-0.4	mA		
l _{OL}	Low-level output current			4			8	mA		
TA	Operating free-air temperature	-55		125	0		70	°C		

[‡] Applies over temperature range -55°C to 70°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST OF	TEST CONDITIONS			8	SN	174ALS0	8	UNIT
PARAMETER	1531 C	UNDITIONS	MIN	TYP¶	MAX	MIN	TYP¶	MAX	UNII
VIK	V _{CC} = 4.5 V,	I _I = -18 mA			-1.5			-1.5	V
Voн	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2			V _{CC} -2	2		V
VOL	V _{CC} = 4.5 V	I _{OL} = 4 mA		0.25	0.4		0.25	0.4	V
VOL	VCC = 4.5 V	I _{OL} = 8 mA					0.35	0.5	V
ΙĮ	V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA
lіН	$V_{CC} = 5.5 V,$	V _I = 2.7 V			20			20	μΑ
Ι _Ι L	$V_{CC} = 5.5 \text{ V},$	V _I = 0.4 V			-0.1			-0.1	mA
IO#	$V_{CC} = 5.5 \text{ V},$	V _O = 2.25 V	-20		-112	-30		-112	mA
Іссн	$V_{CC} = 5.5 V,$	V _I = 4.5 V		1.3	2.4		1.3	2.4	mA
ICCL	$V_{CC} = 5.5 V,$	V _I = 0		2.2	4		2.2	4	mA

[¶] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[§] Applies over temperature range 70°C to 125°C

[#]The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _C C _L R _L T _A	UNIT			
			SN54A	LS08	SN74A	LS08	
			MIN	MAX	MIN	MAX	
^t PLH	A or B	V	2	14	4	14	ns
^t PHL	AOIB	ı	2	12.5	3	10	115

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

,	Supply voltage, V _{CC}	7 V
-	nput voltage, V _I	7 V
	Operating free-air temperature range, T _A : SN54AS08	
	SN74AS08	0°C to 70°C
,	Storage temperature range	-65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54AS08			SN74AS08			UNIT
		MIN NOM MAX MIN NOM M		MAX				
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.8			0.8	V
ІОН	High-level output current			-2			-2	mA
loL	Low-level output current			20			20	mA
TA	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST C	TEST CONDITIONS			SN54AS08			8	UNIT
PARAMETER	IESI C	TEST CONDITIONS		TYP§	MAX	MIN	TYP§	MAX	UNII
VIK	V _{CC} = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V
Voн	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V _{CC} -2	2		V _{CC} -2	2		V
V _{OL}	$V_{CC} = 4.5 \text{ V},$	$I_{OL} = 20 \text{ mA}$		0.35	0.5		0.35	0.5	V
lį	$V_{CC} = 5.5 \text{ V},$	V _I = 7 V			0.1			0.1	mA
lΗ	$V_{CC} = 5.5 \text{ V},$	V _I = 2.7 V			20			20	μΑ
IĮL	$V_{CC} = 5.5 V$,	V _I = 0.4 V			-0.5			-0.5	mA
IO¶	V _{CC} = 5.5 V,	V _O = 2.25 V	-30		-112	-30		-112	mA
ICCH	$V_{CC} = 5.5 \text{ V},$	V _I = 4.5 V		5.8	9.3		5.8	9.3	mA
ICCL	$V_{CC} = 5.5 \text{ V},$	V _I = 0		14.9	24		14.9	24	mA

[§] All typical values are at V_{CC} = 5 V, T_A = 25°C.



The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, Ios.

SN54ALS08, SN54AS08, SN74ALS08, SN74AS08 QUADRUPLE 2-INPUT POSITIVE-AND GATES

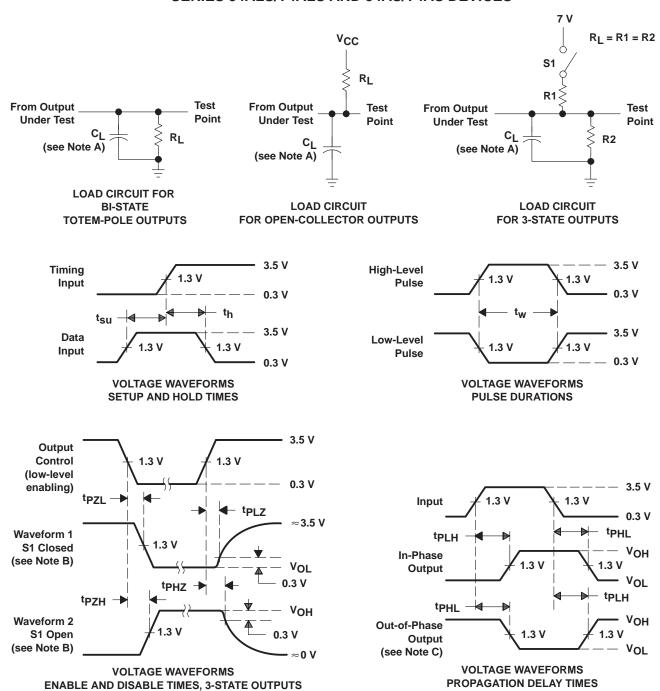
SDAS191A - APRIL 1982 - REVISED DECEMBER 1994

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R_L = 500 Ω , T_A = MIN to MAX †				UNIT
			SN54/		SN74/		
			MIN	MAX	MIN	MAX	
^t PLH	A or B	V	1	6.5	1	5.5	ns
^t PHL	AUD	'	1	6.5	1	5.5	113

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, t_{Γ} = t_{f} = 2 ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms





PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-86842012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
5962-8684201CA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
5962-8684201DA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/37401B2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
JM38510/37401BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54ALS08J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54AS08J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN74ALS08D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS08DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS08DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS08DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS08DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS08DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS08N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74ALS08N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74ALS08NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74ALS08NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS08NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS08D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS08DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS08DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS08DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS08N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74AS08N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74AS08NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74AS08NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS08NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54ALS08FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54ALS08J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC



PACKAGE OPTION ADDENDUM

17-Oct-2005

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SNJ54ALS08W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54AS08FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54AS08J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54AS08W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC

 $^{(1)}$ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in

a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

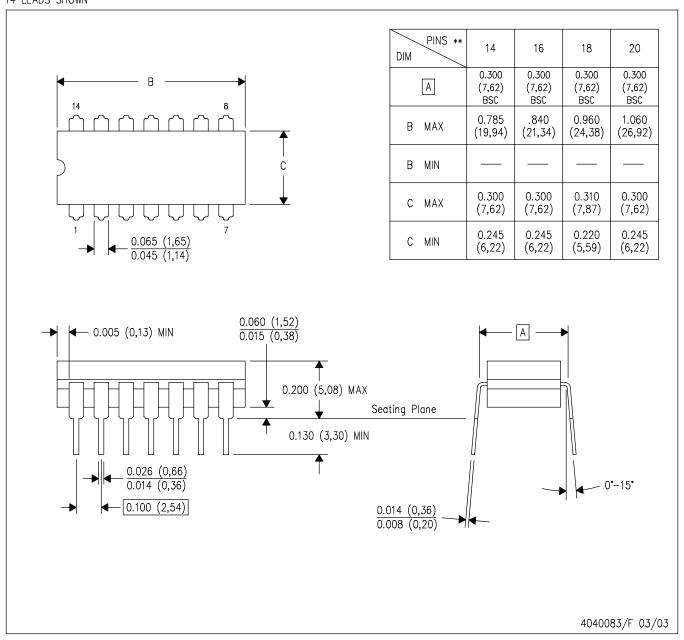
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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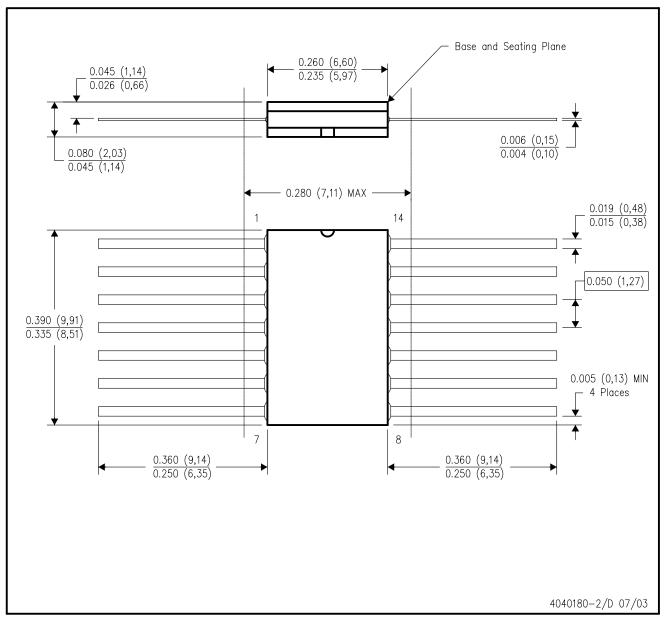
14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



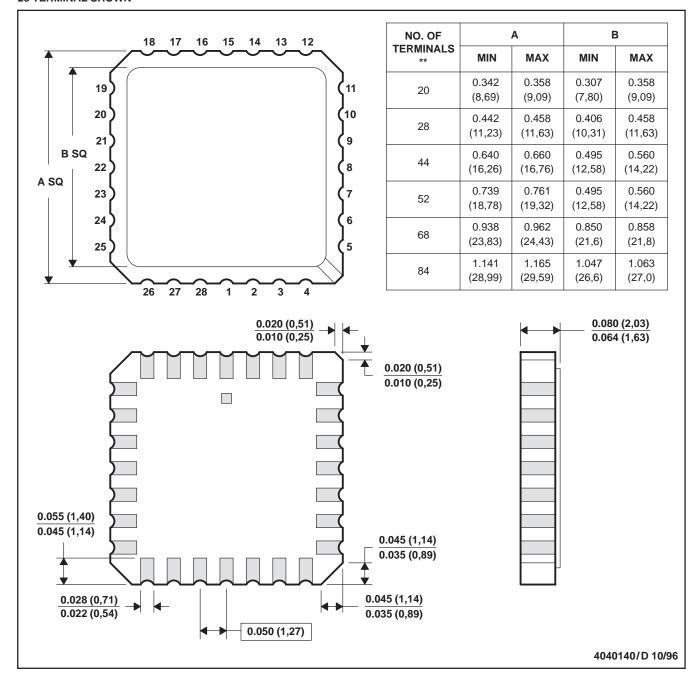
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

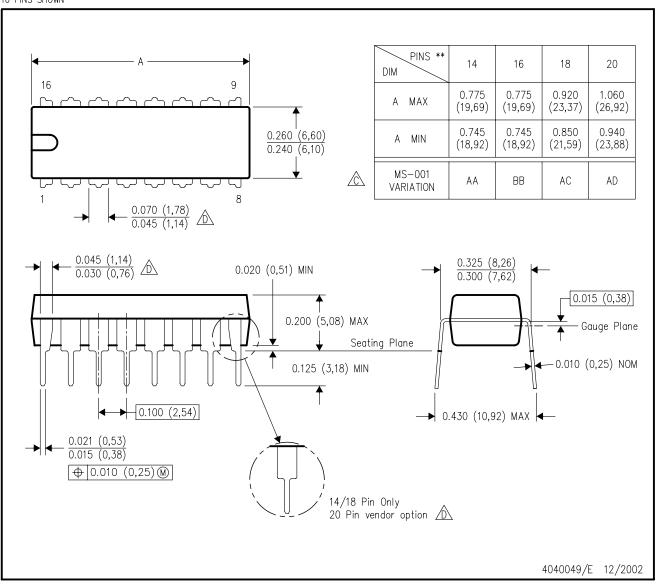
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

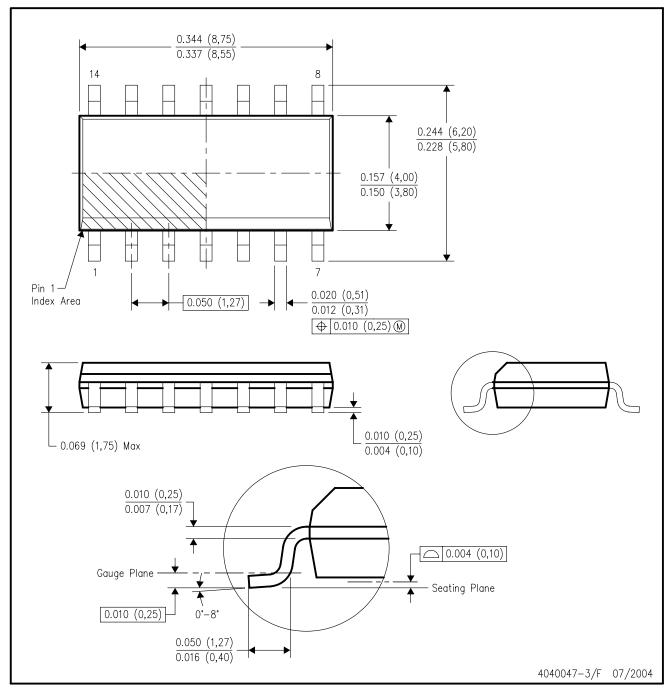


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.

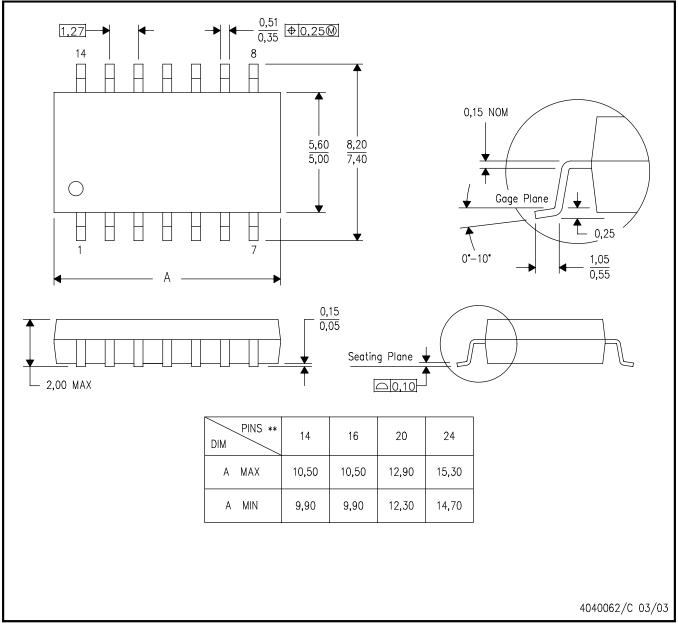


MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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